

# LAMINAR™ E9200

## Dry Film Photoresist

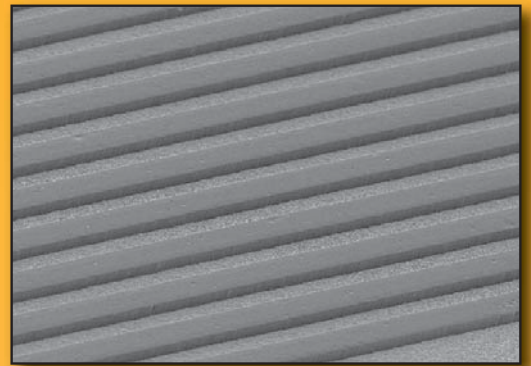
### *Versatile Universal Resist*

#### **Description**

A universal photoresist system that works with nearly all PWB processes including ENIG and Immersion Silver.

#### **Benefits**

- Capable of 1:1 resolution
- Excellent performance in gold plating
- Fast clean processing
- Good donut and isolated resist adhesion
- 2.5 mil (63 $\mu$ ) and 3.0 mil (75 $\mu$ ) thickness
- New! 4.0 mil (100 $\mu$ ) thickness



# LAMINAR™ UD900

## Dry Film Photoresist

### *For Laser Direct Imaging*

#### **Description**

Specifically designed for Laser Direct Imaging (LDI) applications. This resist has demonstrated capability in a wide range of plating and etching applications.

#### **Benefits**

- Fast photo speed
- Capable of better than 1:1 resolution
- Superior fine feature adhesion
- Outstanding performance in acid etching
- Excellent performance in plating applications
- Available in thicknesses up to 3.0 mil (75 $\mu$ )

